DB, DW, OR PW PACKAGE

3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

SLLS349B - JUNE 1999 - REVISED JANUARY 2000

- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Always-Active Noninverting Receiver Output (ROUT1B)
- Operates up to 250 kbit/s
- Low Standby Current . . . 1 µA Typical
- External Capacitors . . . $4 \times 0.1 \mu F$
- Accepts 5-V Logic Input With 3.3-V Supply
- Designed to Be Interchangeable With Maxim MAX3238
- RS-232 Bus-Pin ESD Protection Exceeds ±15-kV Using Human-Body Model (HBM)
- **Applications**
 - Battery-Powered Systems, PDAs, Notebooks, Subnotebooks, Laptops, Palmtop PCs, Hand-Held Equipment, Modems, and Printers
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) **Packages**

,_,	(TOP VI	EW))
C2+[1	28	C1+
GND [2	27] V+
C2-[3	26] _{Vcc}
V-[4	25] C1-
DOUT1[5	24] DIN1
DOUT2[6	23] DIN2
DOUT3[7	22] DIN3
RIN1	8	21] ROUT1
RIN2	9	20	ROUT2
DOUT4[10	19] DIN4
RIN3	11	18] ROUT3
DOUT5	12	17	DIN5
FORCEON[13	16	ROUT1B
FORCEOFF [14	15	INVALID
		wal .	

description

The MAX3238 device consists of five line drivers, three line receivers, and a dual charge-pump circuit with ±15-kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 250 kbit/s, and at a maximum of 30-V/μs driver output slew rate.

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for 30 s, the built-in charge-pump and drivers are powered down, reducing the supply current to 1 μA. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown plus enabled, the device automatically activates once a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than $30 \,\mu s$. $\overline{\text{INVALID}}$ is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μs. Refer to Figure 5 for receiver input levels.

The MAX3238C is characterized for operation from 0°C to 70°C. The MAX3238I is characterized for operation from -40°C to 85°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



AVAILABLE OPTIONS

	Р	ACKAGED DEVICES		
TA	SHRINK SMALL OUTLINE (DB)	SMALL OUTLINE (DW)	THIN SHRINK SMALL OUTLINE (PW)	
0°C to 70°C	MAX3238CDB	MAX3238CDW	MAX3238CPW	
-40°C to 85°C	MAX3238IDB	MAX3238IDW	MAX3238IPW	

The DB, DW, and PW packages are available taped and reeled. Add the suffix R to device type (e.g., MAX3238CDBR).

Function Tables

EACH DRIVER

		INI	PUTS	ОИТРИТ	
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	DOUT	DRIVER STATUS
Х	Χ	L	X	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown plus disabled
L	L	Н	<30 s	Н	Normal operation with
Н	L	Н	<30 s	L	auto-powerdown plus enabled
L	L	Н	>30 s	Z	Powered off by
Н	L	Н	>30 s	Z	auto-powerdown plus feature

H = high level, L = low level, X = irrelevant, Z = high impedance

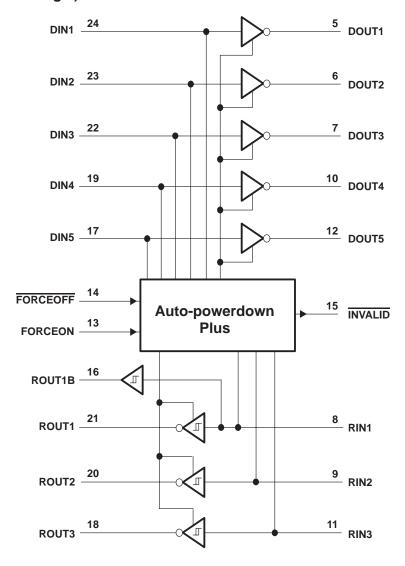
EACH RECEIVER

		INP	UTS	OUTP	UTS	
RIN2	RIN1, RIN3–RIN5	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT	RECEIVER STATUS
L	Χ	L	X	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT1B is active
L	L	Н	<30 s	L	Н	
L	Н	Н	<30 s	L	L	Normal operation with
Н	L	Н	<30 s	Н	Н	auto-powerdown plus
Н	Н	Н	<30 s	Н	L	disabled/enabled
Open	Open	Н	>30 s	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



logic diagram (positive logic)



MAX3238 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	0.3 V to 7 V
Negative output supply voltage range, V– (see Note 1)	0.3 V to -7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver (FORCEOFF, FORCEON)	
Receiver	25 V to 25 V
Output voltage range, V _O : Driver	. -13.2 V to 13.2 V
Receiver (INVALID)0	$0.3 \text{ V to V}_{CC} + 0.3 \text{ V}$
Package thermal impedance, θ _{JA} (see Note 2): DB package	62°C/W
DW package	46°C/W
PW package	62°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3 and Figure 6)

				MIN	NOM	MAX	UNIT
	Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	V
	Supply voltage		V _{CC} = 5 V	4.5	5	5.5	V
\/	Driver and control high-level input voltage	DIN FORCES	V _{CC} = 3.3 V	2			V
VIH	Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V _{CC} = 5 V	2.4			V
VIL	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				0.8	V
٧ _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ _I	Receiver input voltage			-25		25	V
TA	T _A Operating free-air temperature		MAX3238C	0		70	°C
I 'A			MAX3238I	-40		85	O

NOTE 3: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
II	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at V _{CC}		0.5	2	mA
loc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
Icc	Cupply Culton	Auto-powerdown plus enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

 $[\]ddagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 3: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TES	ST CONDITIONS		MIN	TYP [†]	MAX	UNIT
VOH	High-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	GND		5	5.4		V
VOL	Low-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	GND		- 5	-5.4		V
lн	High-level input current	VI = VCC				±0.01	±1	μΑ
Ι _Ι L	Low-level input current	V _I at GND				±0.01	±1	μΑ
laa	Ob and almost a stand a summer t	V _{CC} = 3.6 V,	VO = 0 V			±35	±60	mA
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V			±40	±100	IIIA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V,	V _O = ±2 V		300	10M		Ω
l _{off}	Output leakage current	FORCEOFF = GND,	$V_0 = \pm 12 V$,	$V_{CC} = 0 \text{ to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 $V \pm 0.15$ V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 $V \pm 0.3$ V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS			TYP [†]	MAX	UNIT
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	$R_L = 3 \text{ k}\Omega$, See Figure 1	250			kbit/s
t _{sk(p)}	Pulse skew§	C _L = 150 pF to 2500 pF	R _L = 3 kΩ to 7 kΩ, See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	V/us
SK(II)	(see Figure 1)	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$	C _L = 150 pF to 2500 pF	4		30	ν/μ5

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 $V \pm$ 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 $V \pm$ 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V $_{CC}$ = 5 V \pm 0.5 V.



^{\$} Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

[§] Pulse skew is defined as |tplh - tphl| of each channel of the same device.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
\/	Positive-going input threshold voltage	V _{CC} = 3.3 V		1.5	2.4	V
VIT+	Positive-going input tilleshold voltage	V _{CC} = 5 V		1.8	2.4	
\/	Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.2		V
V _{IT} _	Negative-going input tilleshold voltage	V _{CC} = 5 V	0.8	1.5		V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.3		V
l _{off}	Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_{ } = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3)

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C ₁ = 150 pF, See Figure 3	150)	ns
tPHL	Propagation delay time, high- to low-level output	CL = 150 pr, See rigule 5	150)	ns
t _{en}	Output enable time	C 150 pE B 2 kO See Figure 4	20)	ns
t _{dis}	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	20)	ns
tsk(p)	Pulse skew [‡]	See Figure 3	50)	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

‡ Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 3: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

AUTO-POWERDOWN PLUS SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
V _T –(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
Vон	INVALID high-level output voltage	$I_{OH} = -1 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}	V _{CC} - 0.6			V
VOL	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}			0.4	V

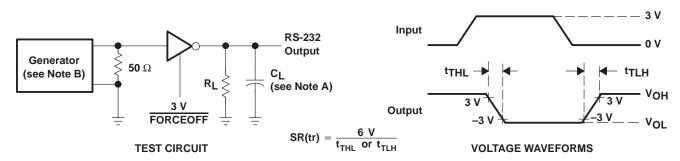
[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN	TYP [†]	MAX	UNIT
^t valid	Propagation delay time, low- to high-level output		0.1		μs
^t invalid	Propagation delay time, high- to low-level output		50		μs
t _{en}	Supply enable time		25		μs
^t dis	Receiver or driver edge to auto-powerdown plus	15	30	60	s

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION

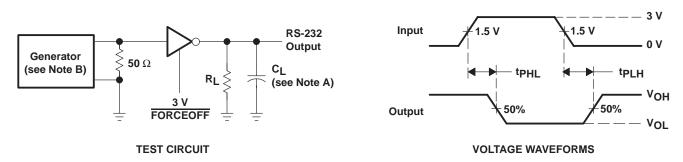


NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 1. Driver Slew Rate

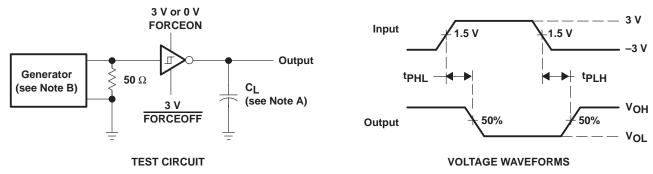




NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

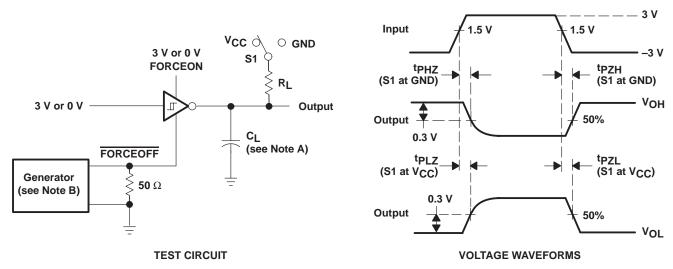
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



NOTES: A. C_I includes probe and jig capacitance.

- B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns, $t_f \le 10$ ns.
- C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- D. tpZL and tpZH are the same as ten.

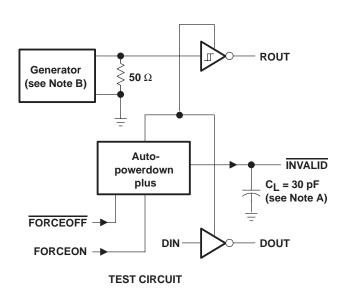
Figure 4. Receiver Enable and Disable Times

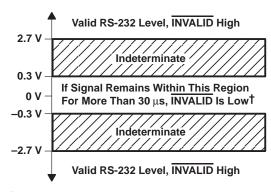


PRODUCT PREVIEW

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PARAMETER MEASUREMENT INFORMATION





 $\mbox{\dag}$ Auto-powerdown plus disables drivers and reduces supply current to 1 $\mu A.$

- NOTES: A. CL includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR = 5 kbit/s, Z_O = 50 Ω , 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

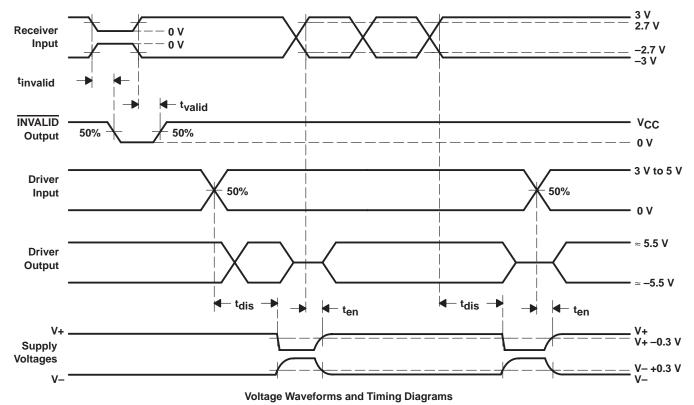
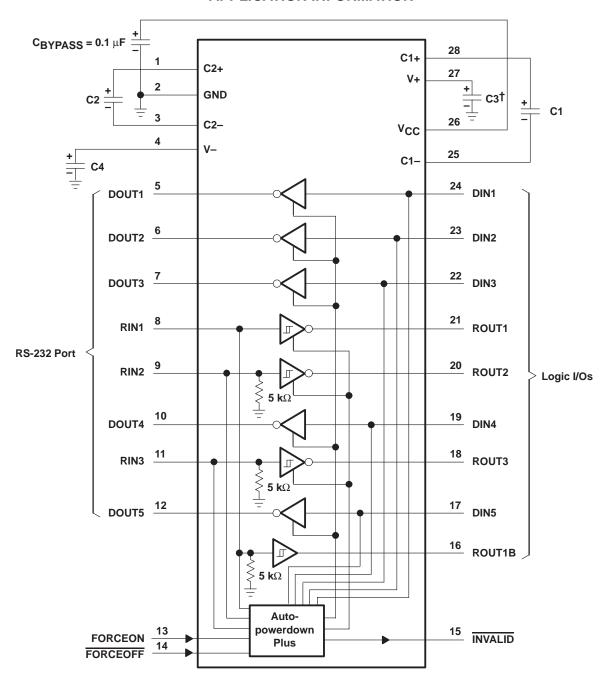


Figure 5. INVALID Propagation Delay Times and Supply Enabling Time



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APPLICATION INFORMATION



 † C3 can be connected to VCC or GND.

NOTE A: Resistor values shown are nominal.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4
$3.3~V\pm0.15~V\\ 3.3~V\pm0.3~V\\ 5~V\pm0.5~V\\ 3~V~to~5.5~V$	0.1 μF 0.22 μF 0.047 μ F 0.22 μF	0.1 μF 0.22 μF 0.33 μF 1 μF

Figure 6. Typical Operating Circuit and Capacitor Values



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